B/O FORM PTO 1595 (1/31/92) Patent and Trademark Office RECORDATION FORM COVER SHEET



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102318235 PATENTS ONLY HITA-0317 To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof Name and Address of Receiving Party(ies): Name of Conveying Party(ies): (1) Teruhisa ICHISE, (2) Hiroyuki UCHIYAMA and Name: Hitachi, Ltd. (3) Masayuki SUZUKI Internal Address: Additional names of conveying parties attached Nature of Conveyance: Street Address: Assignment Merger 6, Kanda Surugadai 4-chome Security Agreement Change of Name City, State, Zip: Other: Chiyoda-ku, Tokyo, Japan Execution Dates: (1) October 3, 2001; (2) September 7, 2001; (3) September 12, 2001 02 (a) Patent Application Number(s): (b) Patent Numbers: 10319551 If this document is being filed together with a new application, the execution dates of the application are: (1) October 3, 2001; (2) September 7, 2001; (3) September 12, 2001 ☐ Additional Numbers Attached. Name and Address of Party to whom Correspondence Fotal Number of Applications and Patents Involved: 1 5 Concerning this Document Should be Mailed: Stanley P. Fisher Total Fee: Name: \$40.00 (37 C.F.R. § 3.41) Reed Smith LLP Address: 3110 Fairview Park Dr. Enclosed. Suite 1400 \boxtimes Authorized to be charged to deposit account. Falls Church, Va. 22042 Deposit Account Number: 08-1480 8. DO NOT USE THIS SPACE Statement and Signature: To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document. **December 13, 2002** Luan Carlos A. Marquez, Registration No. 34,072 Stanley P. Fisher, Registration No. 24, 344

12/18/2002 BNGUYEN1 00000022 10319551

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Total number of pages comprising cover sheet: 1

PATENT REEL: 013584 FRAME: 0970

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND THE METHOD OF PRODUCING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

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4}			
5)			
6)			
7)			

PATENT REEL: 013584 FRAME: 0971

Date Signed (署名日)

RECORDED: 12/16/2002